N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}$ (m Ω)(Typ.)	I _D (A) ^a	Q _g (Typ.)			
30	4.7 at V _{GS} = 10 V	70	35.5 nC			
30	7.6 at $V_{GS} = 4.5 \text{ V}$	70				

FEATURES

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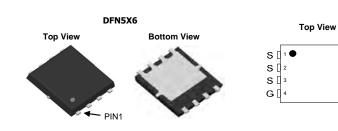
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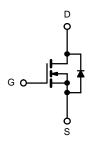
- DT-Trench MOSFET
- 100 % R_g and UIS Tested
- High Current Capability

RoHS

APPLICATIONS

- DC/DC Converters
- · Ideal for high-frequency switching





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V _{DS}	30	V			
Gate-Source Voltage	V _{GS}	± 20				
Ocation of Ducie Company (T. 175 90)2	T _C = 25 °C		70			
Continuous Drain Current (T _J = 175 °C) ^a	T _C = 100 °C	I _D	50	А		
Pulsed Drain Current ^b	I _{DM}	210				
Single Avalanche Energy	E _{AS}	50	mJ			
Mayimum Daway Dissinations	T _C = 25 °C	В	80	W		
Maximum Power Dissipation ^c	T _C = 100 °C	P _D	40	VV		
Operating Junction and Storage Temperature Range		T _J , T _{sta}	- 55 to +175	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) ^d	R _{thJA}	ıJA 45 °C∕\			
Junction-to-Case (Drain)	R _{thJC}	1.87			

Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. $\,$ Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of R_{8JA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper,in a still air environment with Ta=25 °C.



Parameter	Symbol	Test Conditions	Test Conditions Min. Ty		Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = 250 \mu\text{A}$	30			V	
Gate-Source Threshold Voltage	VGS(th)	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.2		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS} _	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Gurrent		V _{DS} = 24 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$ 70				Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A		4.7	4.5	~ 0	
Diain-Source On-State Resistance	NDS(on)	V _{GS} = 4.5 V, I _D = 20 A		7.6	8	mΩ	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 5 V,I _D = 30 A		75		S	
Dynamic ^b			•		•		
Input Capacitance	C _{iss}			1520		pF	
Output Capacitance	C _{oss}	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		193			
Reverse Transfer Capacitance	C _{rss}	1		177			
Total Gate Charge	Q_g			35.5		nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 24 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 30 \text{ A}$		2.7			
Gate-Drain Charge	Q_{gd}	1		8.9			
Gate Resistance	R_{g}	f = 1 MHz		3.9		Ω	
Turn-On Delay Time	t _{d(on)}			9			
Rise Time	t _r	$V_{DD} = 24 \text{ V}, I_D = 30 \text{ A}, R_g = 3 \Omega$		4.5		ns	
Turn-Off DelayTime	t _{d(off)}	V _{GS} = 10 V		21			
Fall Time	t _f]		5			
Drain-Source Body Diode Characteris	ics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			70	А	
Pulse Diode Forward Current (100 μs)	I _{SM}				210		
Body Diode Voltage	, 0				1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	$I_F = 30 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		17		ns	
Body Diode Reverse Recovery Charge	Q_{rr}			26		nC	

Notes:

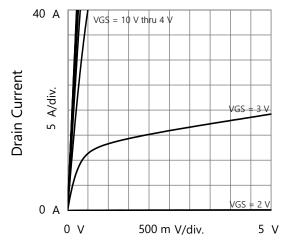
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

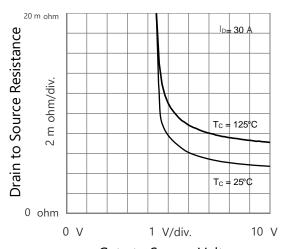
b. Guaranteed by design, not subject to production testing.



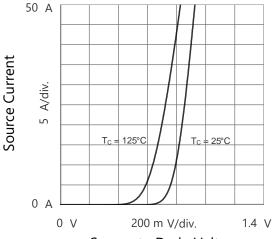
TYPICAL CHARACTERISTICS (25°C, unless otherwise noted)



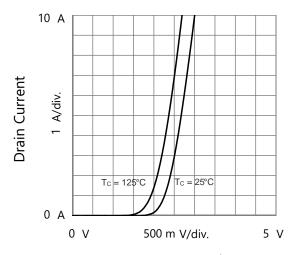
Drain to Source Voltage Output Characteristics



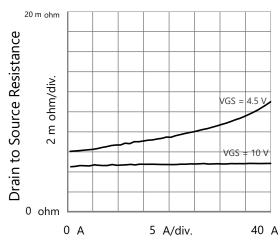
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage



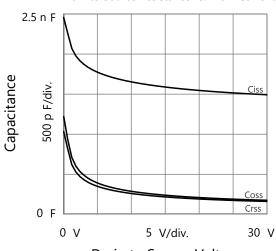
Source to Drain Voltage Body Diode Forward Characteristics



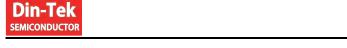
Gate to Source Voltage Transfer Characteristics



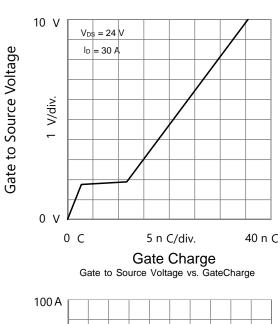
Drain Current
Drain to Source Resistance vs. Drain Current

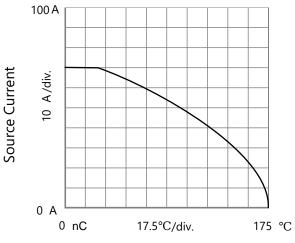


Drain to Source Voltage Capacitances

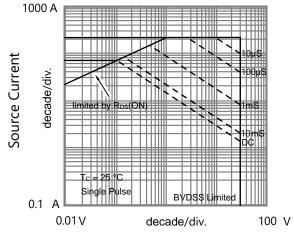


TYPICAL CHARACTERISTICS (25°C, unless otherwise noted)

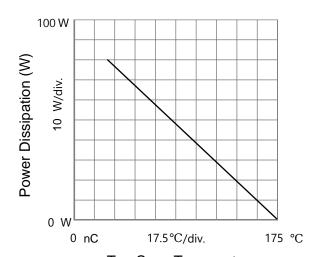






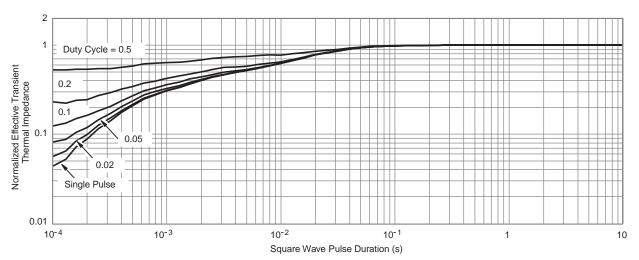


Source to Drain Voltage Safe Operating Area, Junction-to-Ambient



T_C - Case Temperature

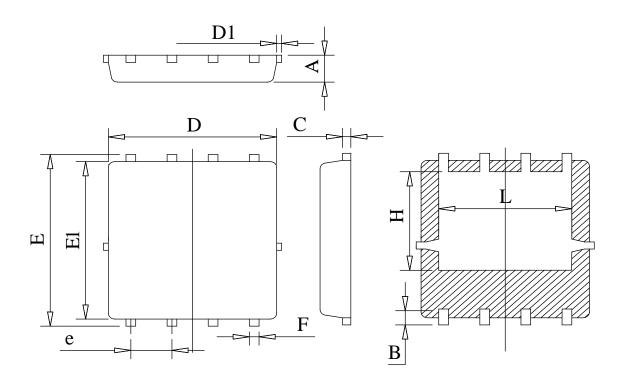
Power Derating



Normalized Thermal Transient Impedance, Junction-to-Case



DFN5X6-8L PACKAGE OUTLINE



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Unit: mm

Symbol	Min	Тур	Max
A	0.78	0.95	1.12
В	0.45	0.58	0.78
C	0.18	0.254	0.36
D	4.70	5.20	5.45
D1			0.18
Е	5.85	6.05	6.25
E1	5.38	5.55	5.98
e	1.15	1.27	1.40
F	0.18	0.30	0.52
Н	3.25	3.47	3.70
L	3.75	4.00	4.25



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